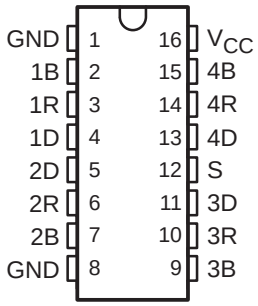
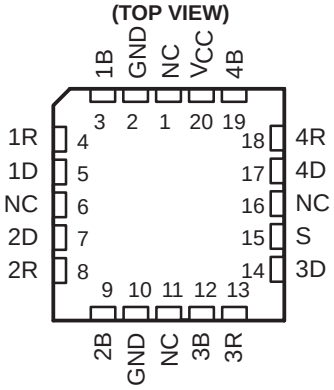
- **Single 5-V Supply**
- **High-Input-Impedance, High-Threshold Receivers**
- **Common Driver Strobe**
- **TTL-Compatible Driver and Strobe Inputs With Clamp Diodes**
- **High-Speed Operation**
- **100-mA Open-Collector Driver Outputs**
- **Four Independent Channels**
- **TTL-Compatible Receiver Output**

SN55138 . . . J OR W PACKAGE
SN75138 . . . D OR N PACKAGE
(TOP VIEW)



SN55138 . . . FK PACKAGE
(TOP VIEW)



NC – No internal connection

description

The SN55138 and SN75138 quadruple bus transceivers are designed for two-way data communication over single-ended transmission lines. Each of the four identical channels consists of a driver with TTL inputs and a receiver with a TTL output. The driver open-collector output is designed to handle loads up to 100-mA open collector. The receiver input is internally connected to the driver output, and has a high impedance to minimize loading of the transmission line. Because of the high driver-output current and the high receiver-input impedance, a very large number (typically hundreds) of transceivers may be connected to a single data bus.

The receiver design also features a threshold of 2.3 V (typical), providing a wider noise margin than would be possible with a receiver having the usual TTL threshold. A strobe turns off all drivers (high impedance) but does not affect receiver operation. These circuits are designed for operation from a single 5-V supply and include a provision to minimize loading of the data bus when the power-supply voltage is zero.

The SN55138 is characterized for operation over the full military temperature range of –55°C to 125°C. The SN75138 is characterized for operation from 0°C to 70°C.

Function Tables

TRANSMITTING

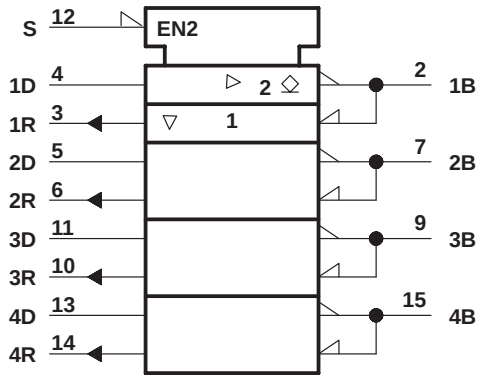
INPUTS		OUTPUTS	
S	D	B	R
L	H	L	H
L	L	H	L

RECEIVING

INPUTS			OUTPUT
S	B	D	R
H	H	X	L
H	L	X	H

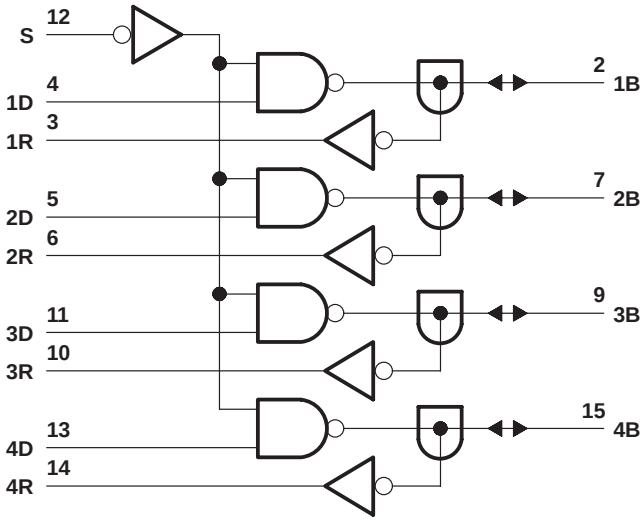
H = high level, L = low level, X = irrelevant

logic symbol†



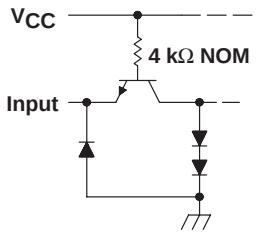
† This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.
Pin numbers shown are for D, J, N, and W packages.

logic diagram (positive logic)

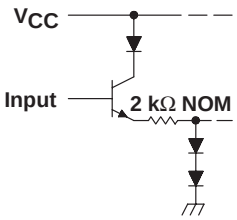


schematics of inputs and outputs

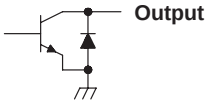
EQUIVALENT OF EACH STROBE AND DRIVER INPUT



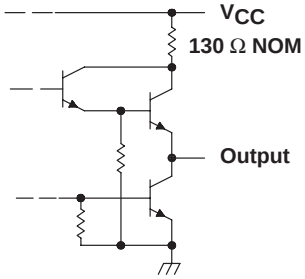
EQUIVALENT OF EACH RECEIVER INPUT



TYPICAL OF ALL DRIVER OUTPUTS



TYPICAL OF ALL RECEIVER OUTPUTS



absolute maximum ratings over operating free-air temperature (unless otherwise noted)†

Supply voltage, V_{CC} (see Note 1) . . . . . 7 V
Input voltage, V_I . . . . . 5.5 V
Driver off-state output voltage . . . . . 7 V
Low-level output current into the driver output . . . . . 150 mA
Continuous total dissipation . . . . . See Dissipation Rating Table
Operating free-air temperature range, T_A: SN55138 . . . . . –55°C to 125°C
SN75138 . . . . . 0°C to 70°C
Storage temperature range, T_{stg} . . . . . –65°C to 150°C
Lead temperature 1,6 mm (1/16 inch) from case for 10 seconds: D, N, or W package . . . . . 260°C
Case temperature for 60 seconds, T_C: FK package . . . . . 260°C
Lead temperature 1,6 mm (1/16 inch) from case for 60 seconds: J package . . . . . 300°C

† Stresses beyond those listed under “absolute maximum ratings” may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under “recommended operating conditions” is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to both ground terminals connected together.

DISSIPATION RATING TABLE

PACKAGE	$T_A \le 25°C$ POWER RATING	DERATING FACTOR ABOVE $T_A = 25°C$	$T_A = 70°C$ POWER RATING	$T_A = 125°C$ POWER RATING
D	950 mW	7.6 mW/°C	608 mW	—
FK‡	1375 mW	11.0 mW/°C	880 mW	275 mW
J‡	1375 mW	11.0 mW/°C	880 mW	275 mW
N	1150 mW	9.2 mW/°C	736 mW	—
W	1000 mW	8.0 mW/°C	640 mW	200 mW

‡ In the FK and J packages, the SN55138 chip is alloy mounted.

recommended operating conditions

		SN55138			SN75138			UNIT
		MIN	NOM	MAX	MIN	NOM	MAX	
Supply voltage, V_{CC}		4.5		5.5	4.75	5	5.25	V
High-level input voltage, V_{IH}	Driver or strobe	2			2			V
	Receiver	3.2			2.9			
Low-level input voltage, V_{IL}	Driver or strobe			0.8			0.8	V
	Receiver			1.5			1.8	
High-level output current, I_{OH}	Receiver output			–400			–400	μA
Low-level output current, I_{OL}	Driver output			100			100	mA
	Receiver output			16			16	
Operating free-air temperature, T_A		–55		125	0		70	°C

electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER			TEST CONDITIONS†		SN55138			SN75138			UNIT
					MIN	TYP‡	MAX	MIN	TYP‡	MAX	
V_{IK}	Input clamp voltage	Driver or strobe	V_{CC} = MIN,	I_I = –12 mA			–1.5			–1.5	V
V_{OH}	High-level output voltage	Receiver	V_{CC} = MIN, $V_{IL(R)}$ = V_{IL} max,	$V_{IH(S)}$ = 2 V, I_{OH} = –400 μA	2.4	3.5		2.4	3.5		V
V_{OL}	Low-level output voltage	Driver	V_{CC} = MIN, $V_{IL(S)}$ = 0.8 V,	$V_{IH(D)}$ = 2 V, I_{OL} = 100 mA			0.45			0.45	V
		Receiver	V_{CC} = MIN, $V_{IH(S)}$ = 2 V,	$V_{IH(R)}$ = V_{IH} min, I_{OL} = 16 mA			0.4			0.4	
I_I(max)	Input current at maximum input voltage	Driver or strobe	V_{CC} = MAX,	V_I = V_{CC}			1			1	mA
I_{IH}	High-level input current	Driver or strobe	V_{CC} = MAX,	V_I = 2.4 V			40			40	μA
		Receiver	V_{CC} = 5 V, $V_{I(S)}$ = 2 V	$V_{I(R)}$ = 4.5 V,		25	300		25	300	
I_{IL}	Low-level input current	Driver or strobe	V_{CC} = MAX,	V_I = 0.4 V		–1	–1.6		–1	–1.6	mA
		Receiver	V_{CC} = MAX, $V_{I(S)}$ = 2 V	$V_{I(R)}$ = 0.45 V,			–50			–50	μA
$I_{I(off)}$	Input current with power off	Receiver	V_{CC} = 0,	V_I = 4.5 V		1.1	1.5		1.1	1.5	mA
I_{OS}	Short-circuit output current§	Receiver	V_{CC} = MAX		–20		–55	–18		–55	mA
I_{CC}	Supply current	All driver outputs low	V_{CC} = MAX, $V_{I(S)}$ = 0.8 V	$V_{I(D)}$ = 2 V,		50	65		50	65	mA
		All driver outputs high	V_{CC} = MAX, $V_{I(S)}$ = 2 V, Receiver outputs open	$V_{I(R)}$ = 3.5 V,		42	55		42	55	

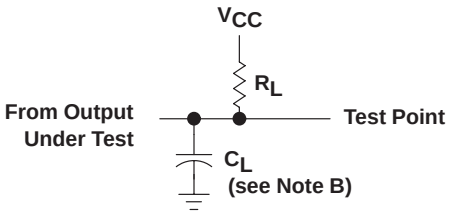
† For conditions shown as MIN or MAX, use the appropriate value specified under recommended operating conditions. Parenthetical letters D, R, and S used with V_I refer to the driver input, receiver input, and strobe input, respectively.
‡ All typical values are at V_{CC} = 5 V, T_A = 25°C.
§ Not more than one output should be shorted at a time.

switching characteristics, V_{CC} = 5 V, T_A = 25°C

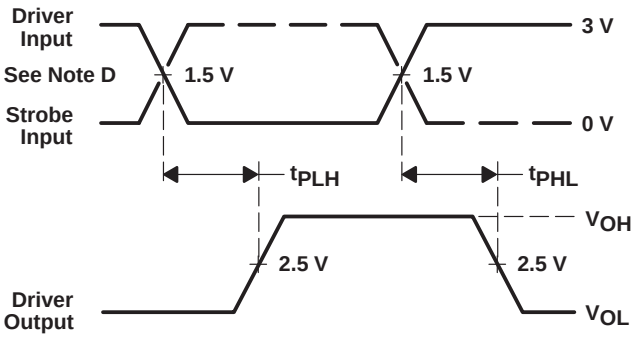
PARAMETER¶	FROM (INPUT)	TO (OUTPUT)	TEST CONDITIONS		MIN	TYP	MAX	UNIT
t_{PLH}	Driver	Driver	C_L = 50 pF, R_L = 50 Ω,	See Figure 1		15	24	ns
t_{PHL}						14	24	
t_{PLH}	Strobe	Driver				18	28	ns
t_{PHL}						22	32	
t_{PLH}	Receiver	Receiver	C_L = 15 pF R_L = 400 Ω,	See Figure 2		7	15	ns
t_{PHL}						8	15	

¶ t_{PLH} = propagation delay time, low- to high-level output
t_{PHL} = propagation delay time, high- to low-level output

PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT

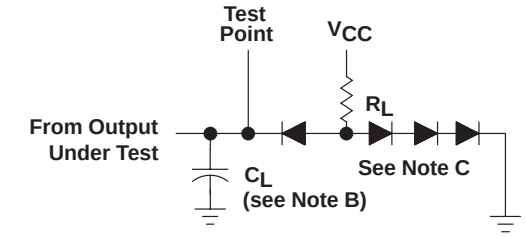


VOLTAGE WAVEFORMS

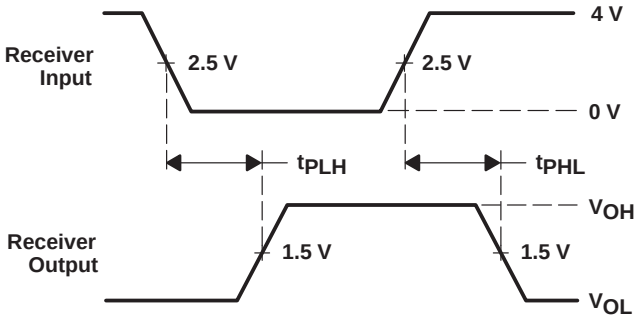
NOTES: A. Input pulses are supplied by generators having the following characteristics: t_W = 100 ns, PRR ≤ 1 MHz, t_r ≤ 10 ns, t_f ≤ 10 ns, $Z_O \approx 50\ \Omega$.
B. C_L includes probe and jig capacitance.
C. All diodes are 1N916 or 1N3064.
D. When testing driver input (solid line) strobe must be low; when testing strobe input (dashed line) driver input must be high.

Figure 1. Propagation Delay Times From Data and Strobe Inputs

PARAMETER MEASUREMENT INFORMATION



TEST CIRCUIT



VOLTAGE WAVEFORMS

NOTES: A. Input pulses are supplied by generators having the following characteristics: t_W = 100 ns, PRR ≤ 1 MHz, t_r ≤ 10 ns, t_f ≤ 10 ns, $Z_O \approx 50\ \Omega$.
B. C_L includes probe and jig capacitance.
C. All diodes are 1N916 or 1N3064.
D. When testing driver input (solid line) strobe must be low; when testing strobe input (dashed line) driver input must be high.

Figure 2. Propagation Delay Times From Receiver Input

TYPICAL CHARACTERISTICS†

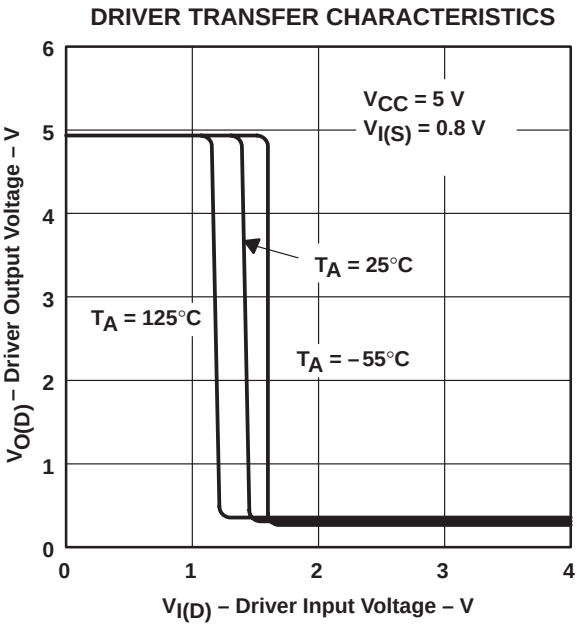


Figure 3

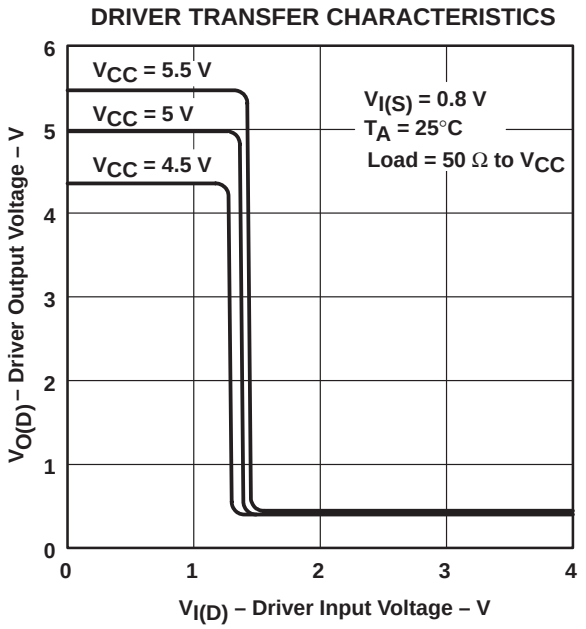


Figure 4

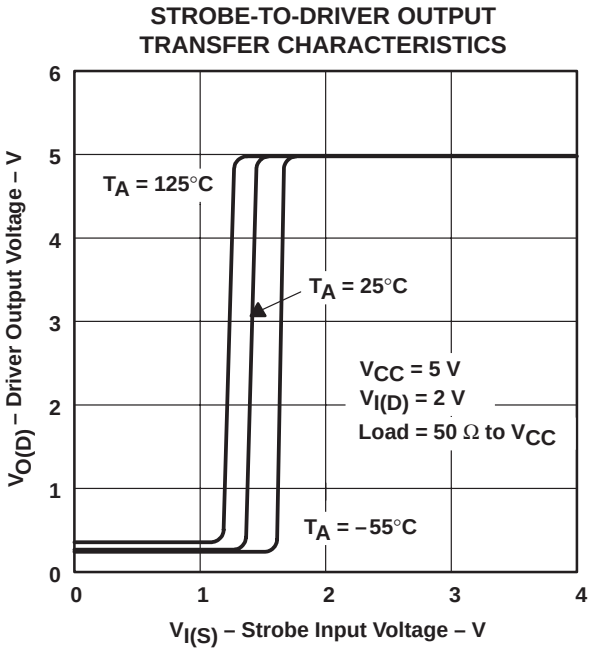


Figure 5

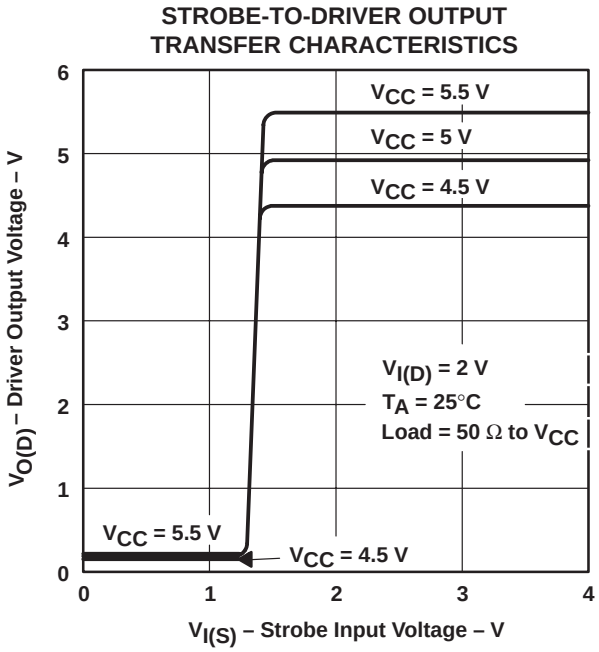


Figure 6

† Data for temperatures below 0°C and above 70°C is applicable to SN55138 circuits only.

TYPICAL CHARACTERISTICS†

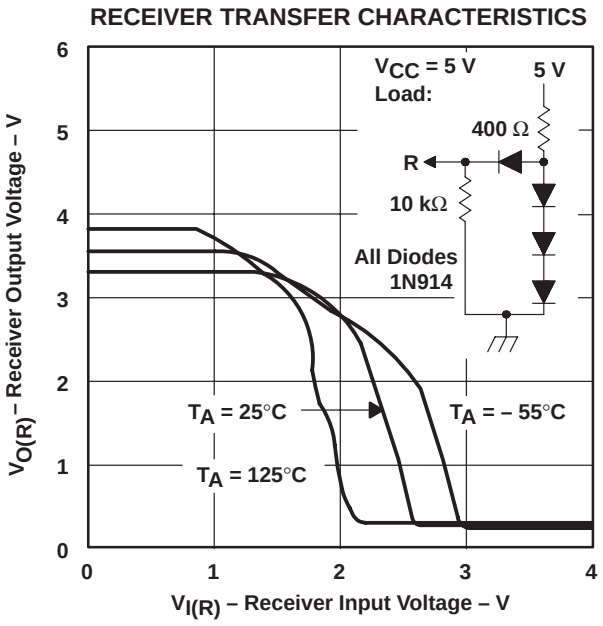


Figure 7

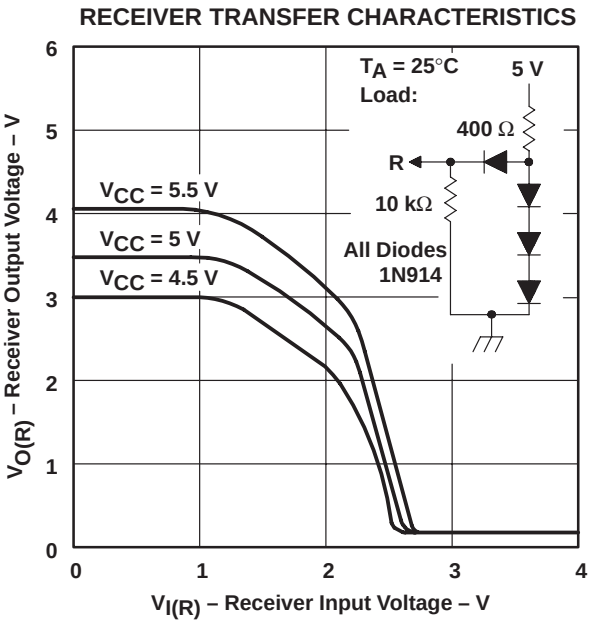


Figure 8

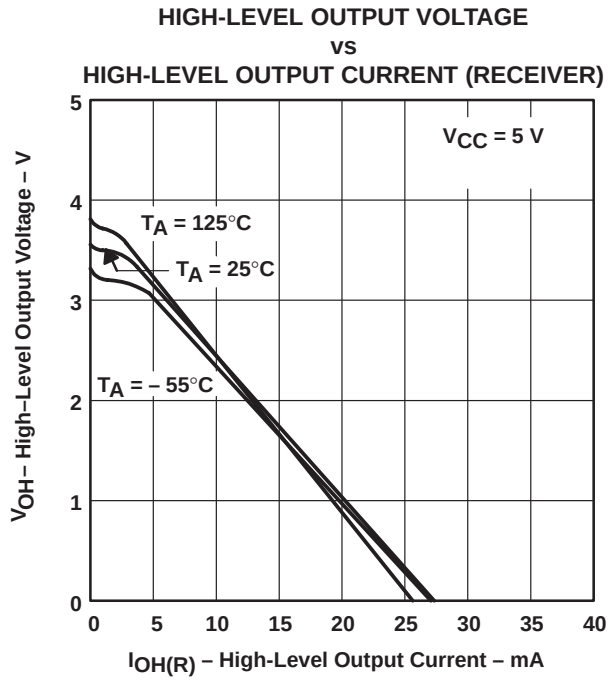


Figure 9

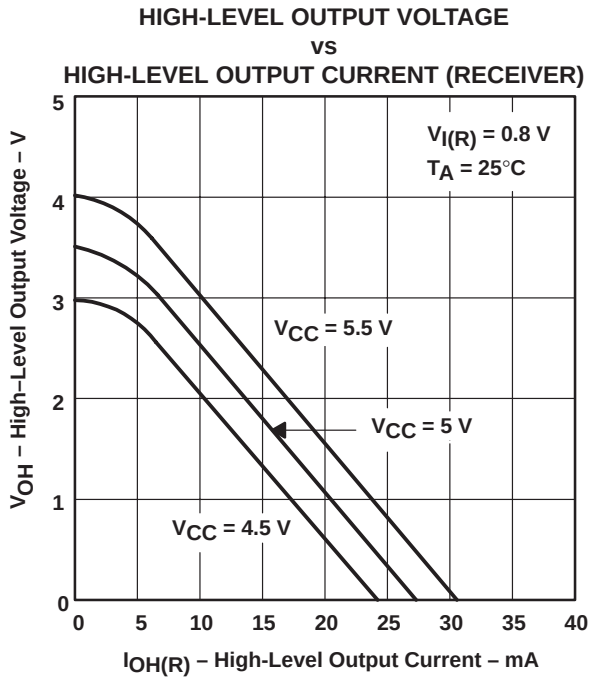


Figure 10

† Data for temperatures below 0°C and above 70°C is applicable to SN55138 circuits only.

TYPICAL CHARACTERISTICS†

LOW-LEVEL OUTPUT VOLTAGE vs LOW-LEVEL OUTPUT CURRENT (RECEIVER)

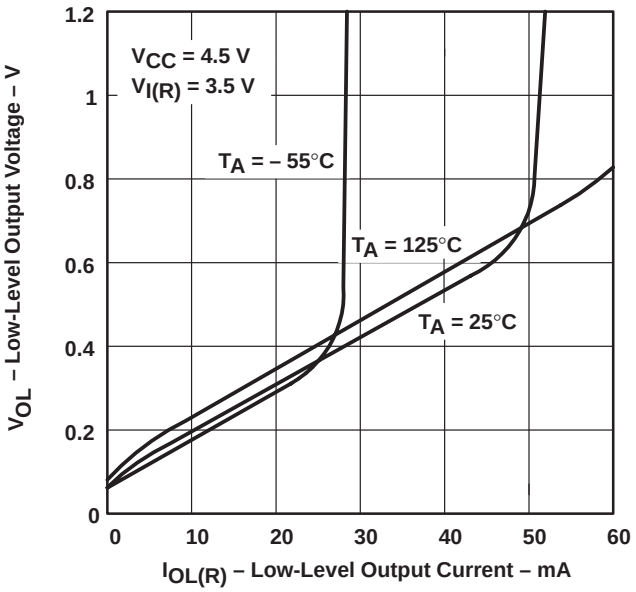


Figure 11

LOW-LEVEL OUTPUT VOLTAGE vs LOW-LEVEL OUTPUT CURRENT (DRIVER)

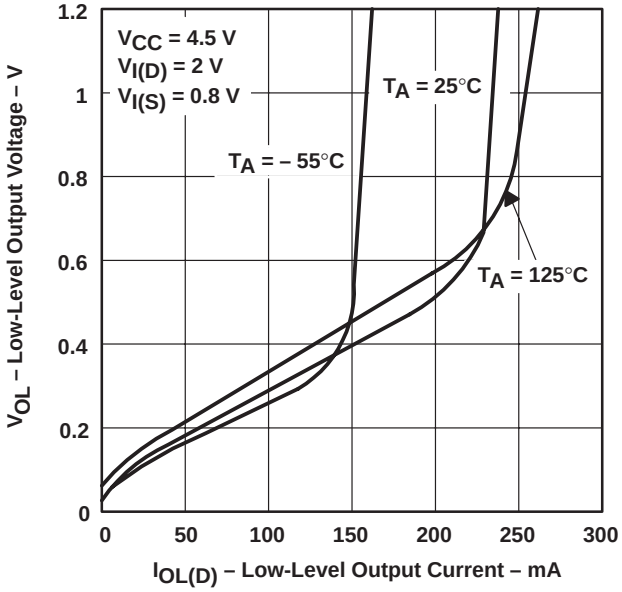


Figure 12

RECEIVER INPUT CURRENT vs RECEIVER INPUT VOLTAGE

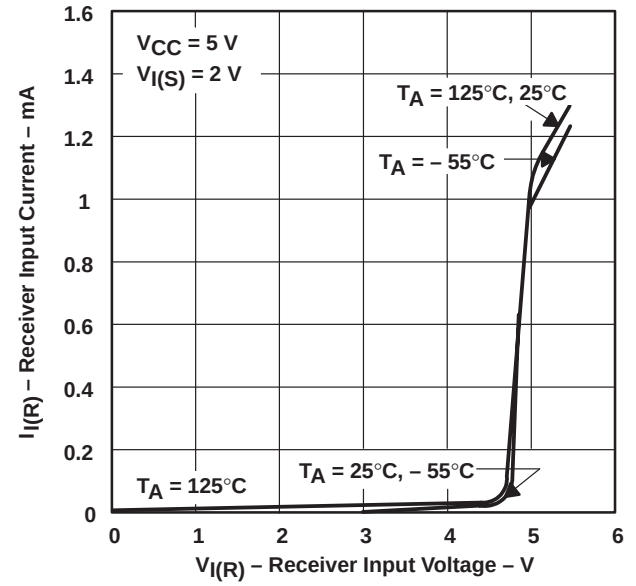


Figure 13

RECEIVER INPUT CURRENT vs RECEIVER INPUT VOLTAGE

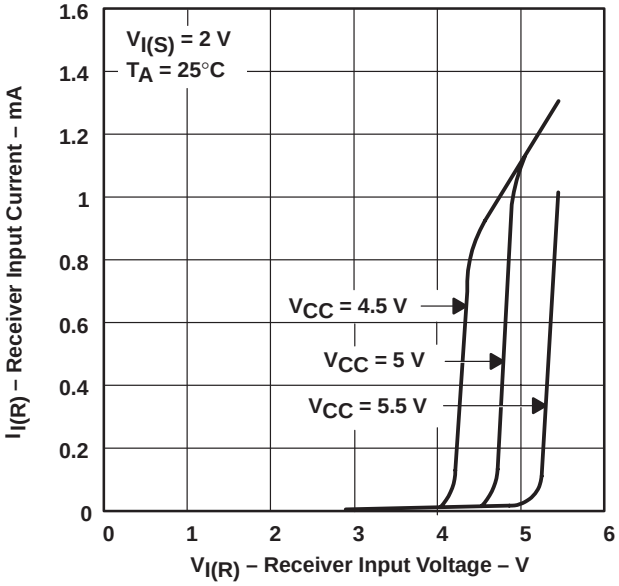


Figure 14

† Data for temperatures below 0°C and above 70°C is applicable to SN55138 circuits only.

TYPICAL CHARACTERISTICS†

SUPPLY CURRENT vs SUPPLY VOLTAGE (ALL DRIVER OUTPUTS LOW)

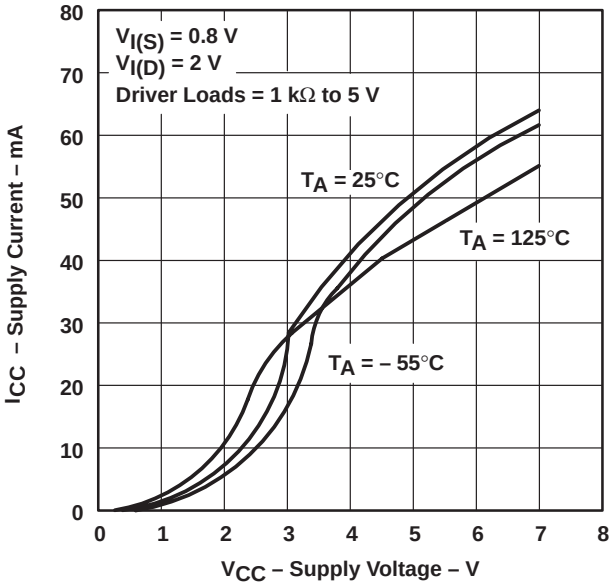


Figure 15

SUPPLY CURRENT vs SUPPLY VOLTAGE

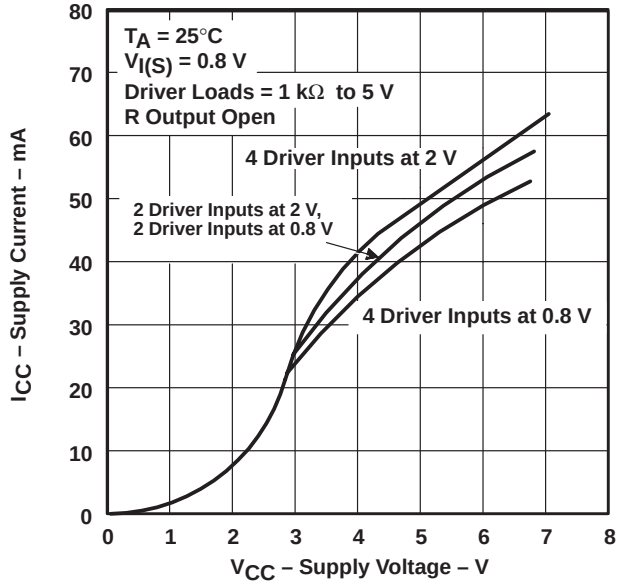


Figure 16

PROPAGATION DELAY TIMES vs FREE-AIR TEMPERATURE

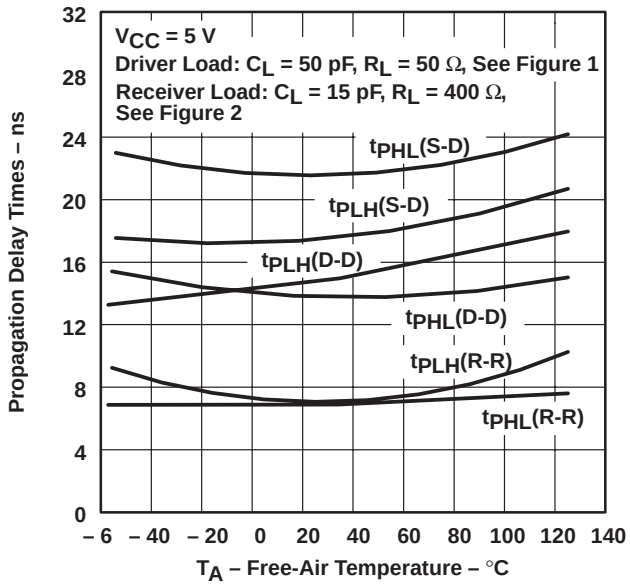


Figure 17

PROPAGATION DELAY TIMES vs SUPPLY VOLTAGE

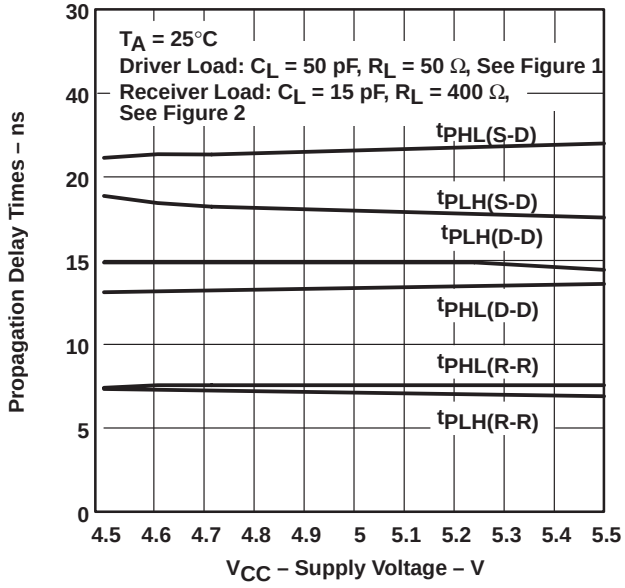


Figure 18

† Data for temperatures below 0°C and above 70°C is applicable to SN55138 circuits only.

TYPICAL CHARACTERISTICS

DRIVER
PROPAGATION DELAY TIMES
vs
LOAD CAPACITANCE

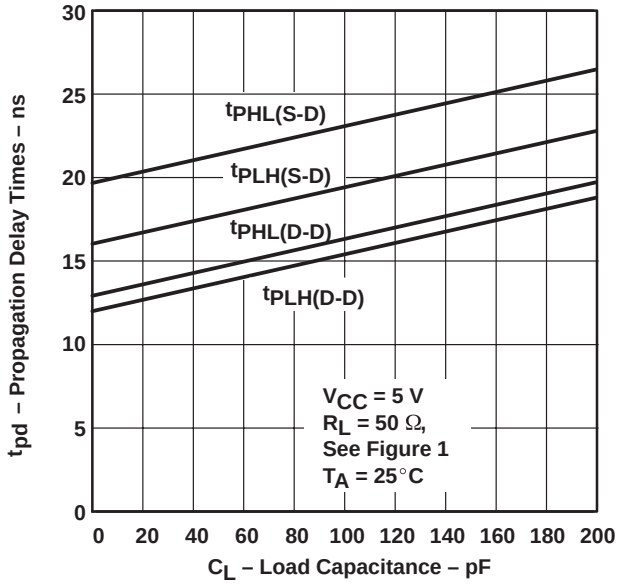


Figure 19

RECEIVER
PROPAGATION DELAY TIMES
vs
LOAD CAPACITANCE

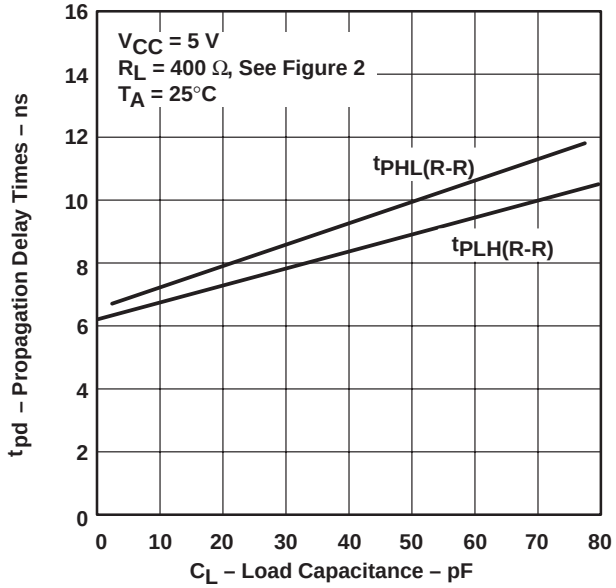
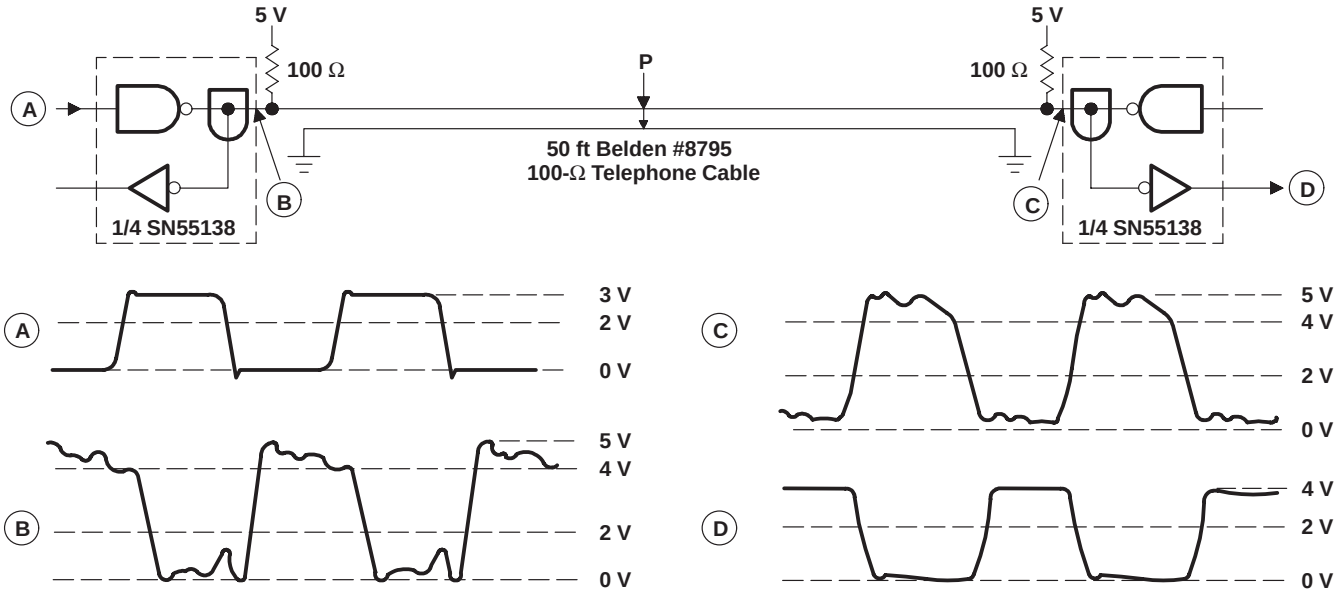


Figure 20

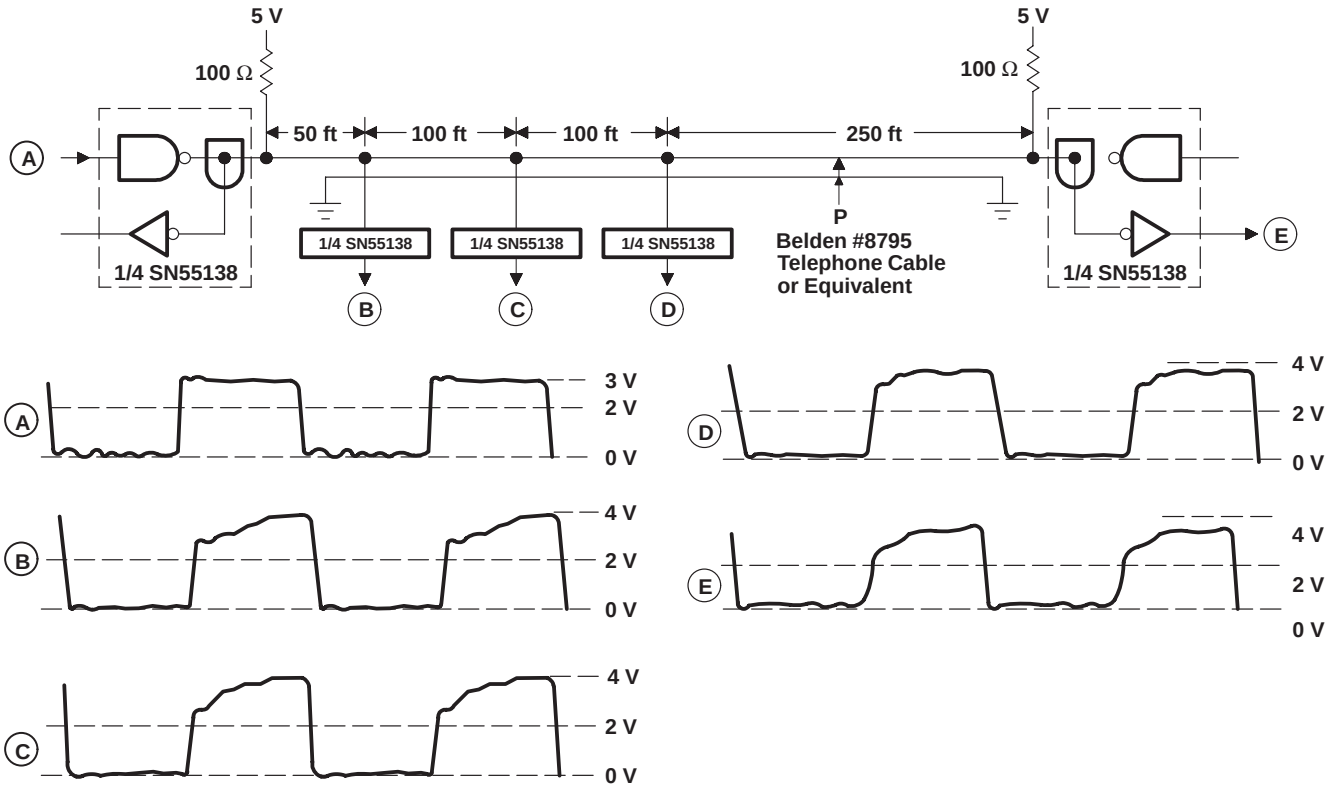
APPLICATION INFORMATION



TYPICAL VOLTAGE WAVEFORMS

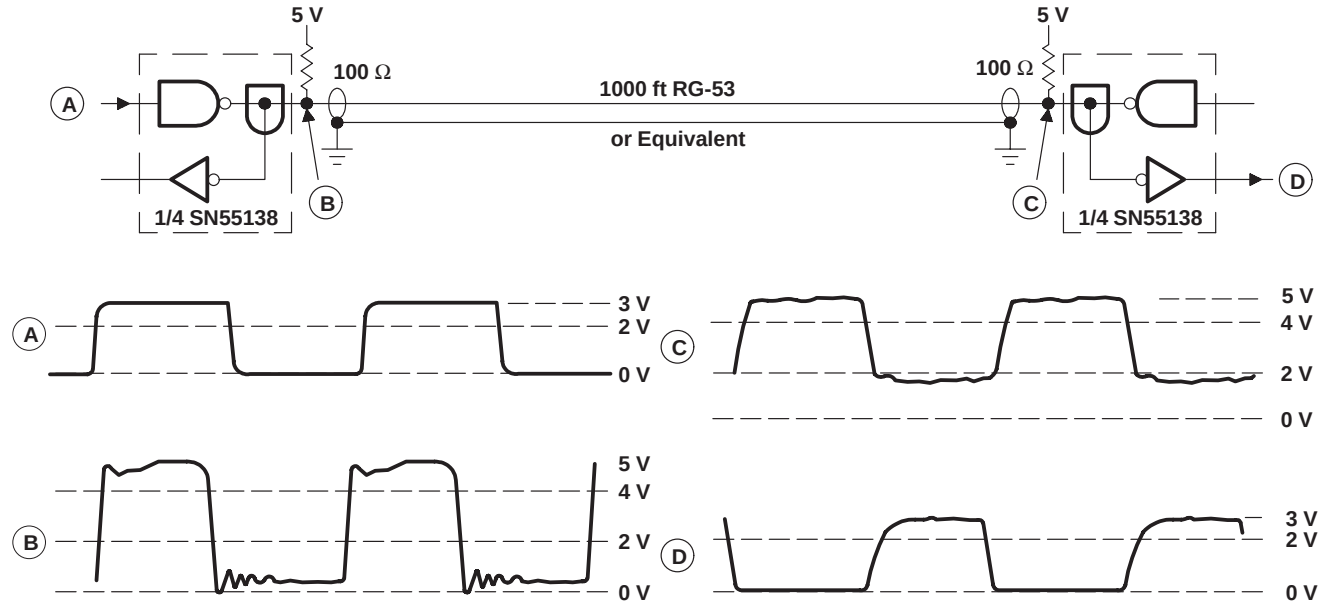
Figure 21. Point-to-Point Communication Over 50 Feet of Twisted Pair at 5 MHz

APPLICATION INFORMATION



TYPICAL VOLTAGE WAVEFORMS

Figure 22. Party-Line Communication on 500 Feet of Twisted Pair at 1 MHz



TYPICAL VOLTAGE WAVEFORMS

Figure 23. Point-to-Point Communication Over 1000 Feet of Coaxial Cable at 1 MHz

PACKAGING INFORMATION

Orderable Device	Status (1)	Package Type	Package Drawing	Pins	Package Qty	Eco Plan (2)	Lead/Ball Finish	MSL Peak Temp (3)
SN55138J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SN75138D	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75138DE4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75138DG4	ACTIVE	SOIC	D	16	40	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75138DR	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75138DRE4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75138DRG4	ACTIVE	SOIC	D	16	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75138N	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75138NE4	ACTIVE	PDIP	N	16	25	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
SN75138NSR	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75138NSRE4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SN75138NSRG4	ACTIVE	SO	NS	16	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
SNJ55138FK	OBSOLETE	LCCC	FK	20		TBD	Call TI	Call TI
SNJ55138J	OBSOLETE	CDIP	J	16		TBD	Call TI	Call TI
SNJ55138W	OBSOLETE	CFP	W	16		TBD	Call TI	Call TI

(1) The marketing status values are defined as follows:
ACTIVE: Product device recommended for new designs.
LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.
NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.
PREVIEW: Device has been announced but is not in production. Samples may or may not be available.
OBSOLETE: TI has discontinued the production of the device.

(2) Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check http://www.ti.com/productcontent for the latest availability information and additional product content details.
TBD: The Pb-Free/Green conversion plan has not been defined.
Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.
Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.
Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

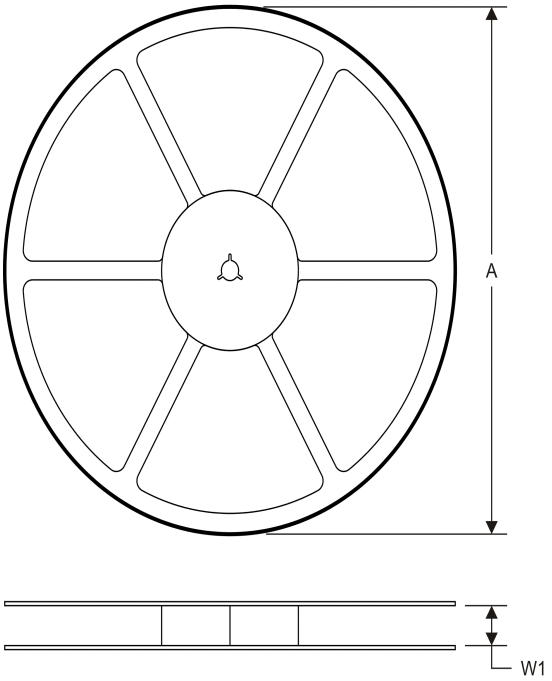
(3) MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

reasonable steps to provide representative and accurate information but may not have conducted destructive testing or chemical analysis on incoming materials and chemicals. TI and TI suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.

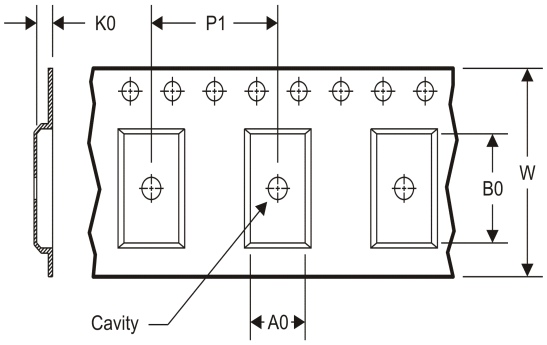
In no event shall TI's liability arising out of such information exceed the total purchase price of the TI part(s) at issue in this document sold by TI to Customer on an annual basis.

TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSIONS



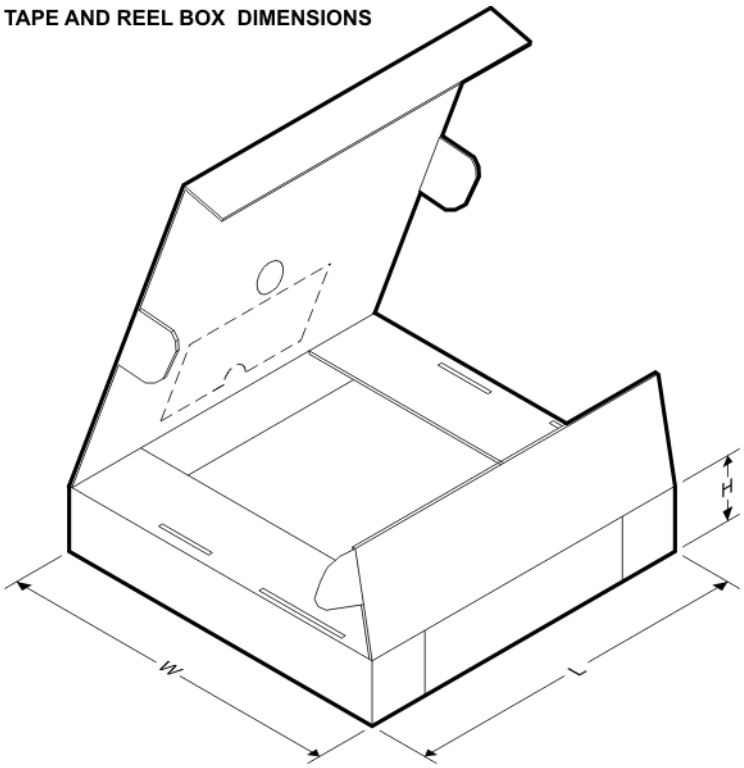
A0	Dimension designed to accommodate the component width
B0	Dimension designed to accommodate the component length
K0	Dimension designed to accommodate the component thickness
W	Overall width of the carrier tape
P1	Pitch between successive cavity centers

TAPE AND REEL INFORMATION

*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
SN75138DR	SOIC	D	16	2500	330.0	16.4	6.5	10.3	2.1	8.0	16.0	Q1
SN75138NSR	SO	NS	16	2000	330.0	16.4	8.2	10.5	2.5	12.0	16.0	Q1

TAPE AND REEL BOX DIMENSIONS



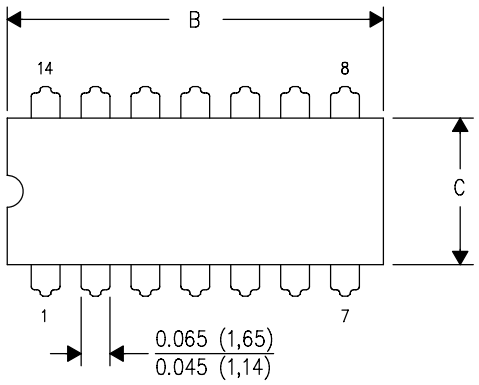
*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
SN75138DR	SOIC	D	16	2500	333.2	345.9	28.6
SN75138NSR	SO	NS	16	2000	367.0	367.0	38.0

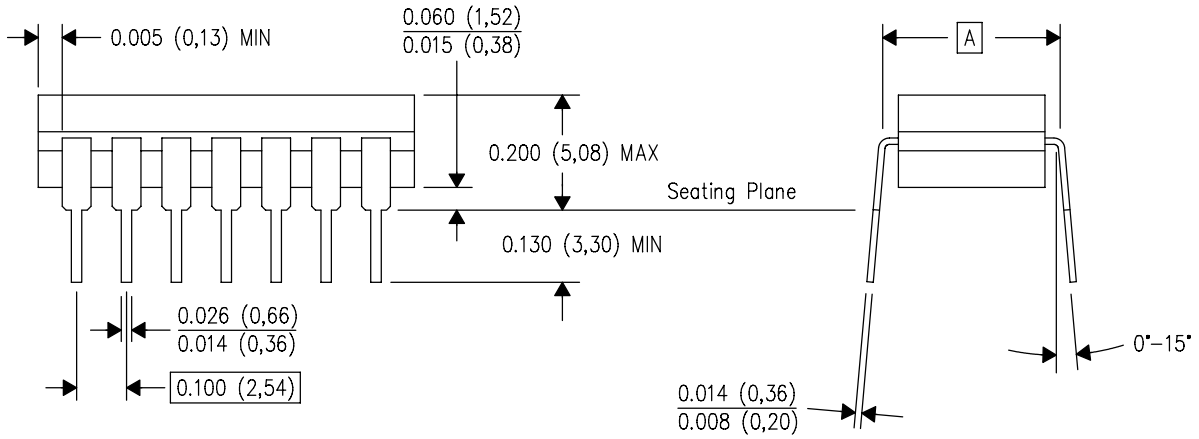
J (R–GDIP–T**)

14 LEADS SHOWN

CERAMIC DUAL IN–LINE PACKAGE



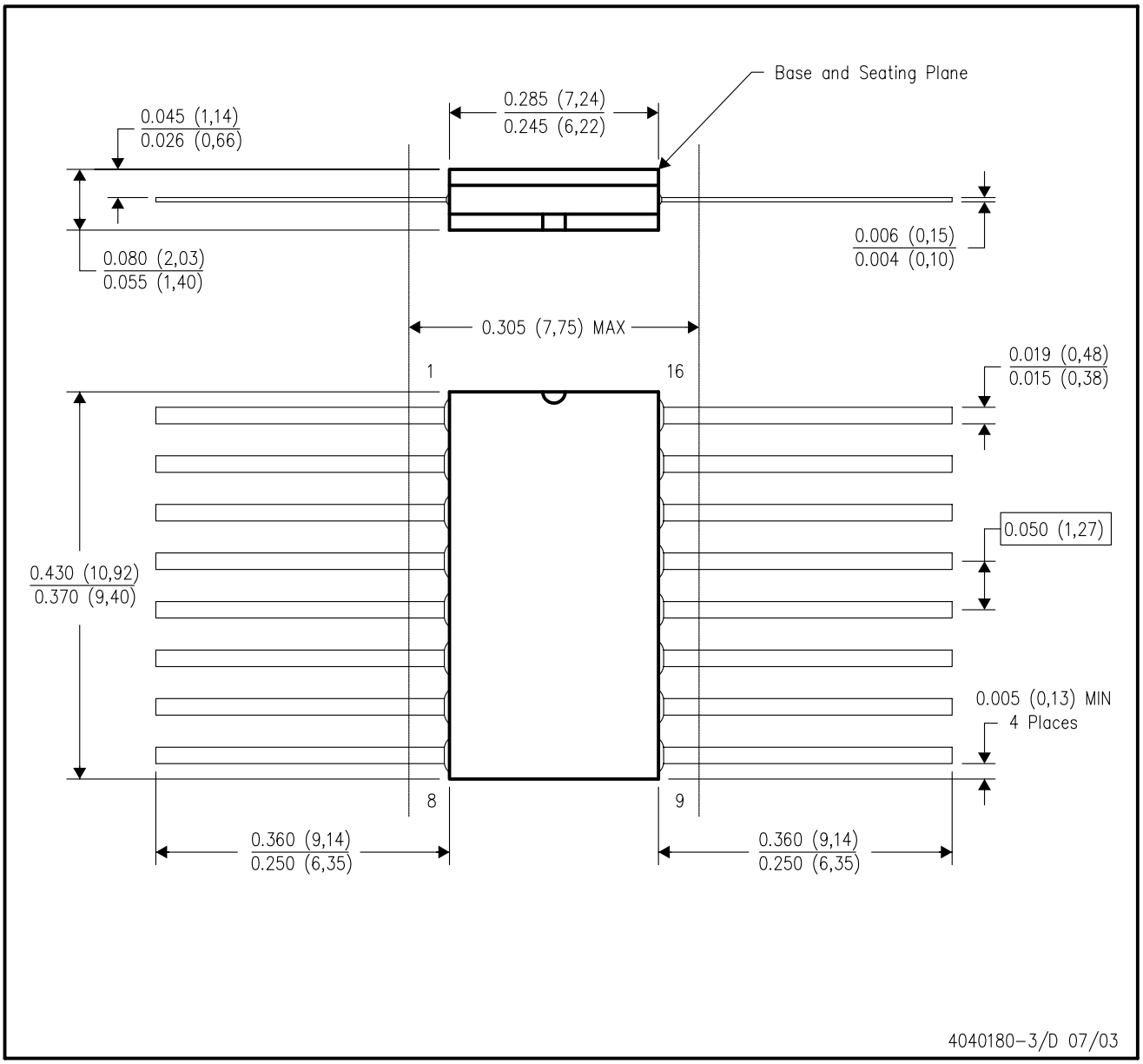
DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



4040083/F 03/03

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package is hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
E. Falls within MIL STD 1835 GDIP1–T14, GDIP1–T16, GDIP1–T18 and GDIP1–T20.

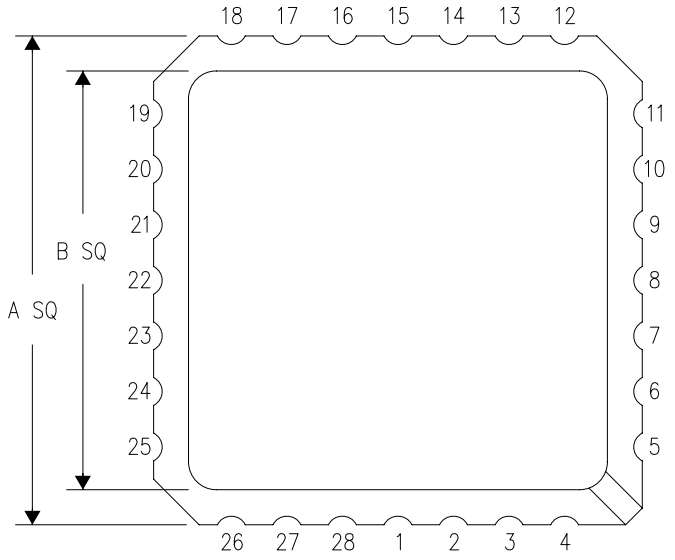
W (R–GDFP–F16) CERAMIC DUAL FLATPACK



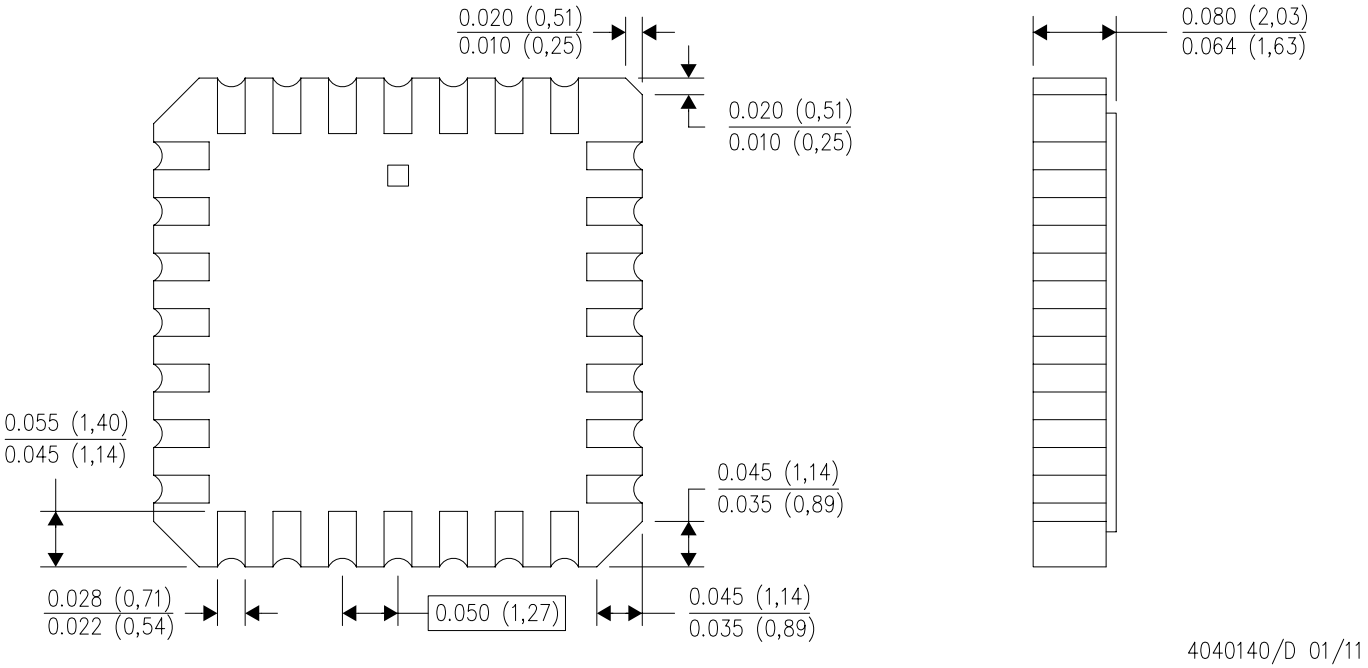
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a ceramic lid using glass frit.
D. Index point is provided on cap for terminal identification only.
E. Falls within MIL STD 1835 GDFP1–F16 and JEDEC MO–092AC

FK (S–CQCC–N**) LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN



NO. OF TERMINALS **	A		B	
	MIN	MAX	MIN	MAX
20	0.342 (8,69)	0.358 (9,09)	0.307 (7,80)	0.358 (9,09)
28	0.442 (11,23)	0.458 (11,63)	0.406 (10,31)	0.458 (11,63)
44	0.640 (16,26)	0.660 (16,76)	0.495 (12,58)	0.560 (14,22)
52	0.740 (18,78)	0.761 (19,32)	0.495 (12,58)	0.560 (14,22)
68	0.938 (23,83)	0.962 (24,43)	0.850 (21,6)	0.858 (21,8)
84	1.141 (28,99)	1.165 (29,59)	1.047 (26,6)	1.063 (27,0)



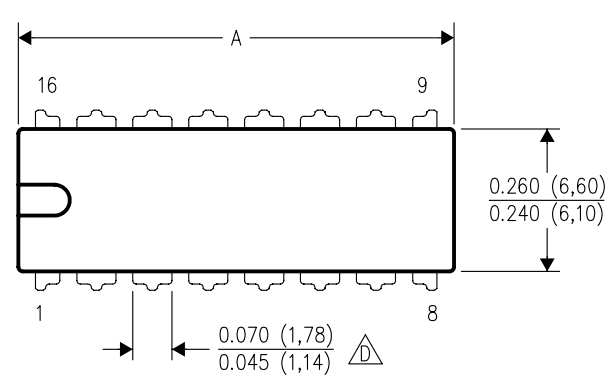
4040140/D 01/11

NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. This package can be hermetically sealed with a metal lid.
D. Falls within JEDEC MS–004

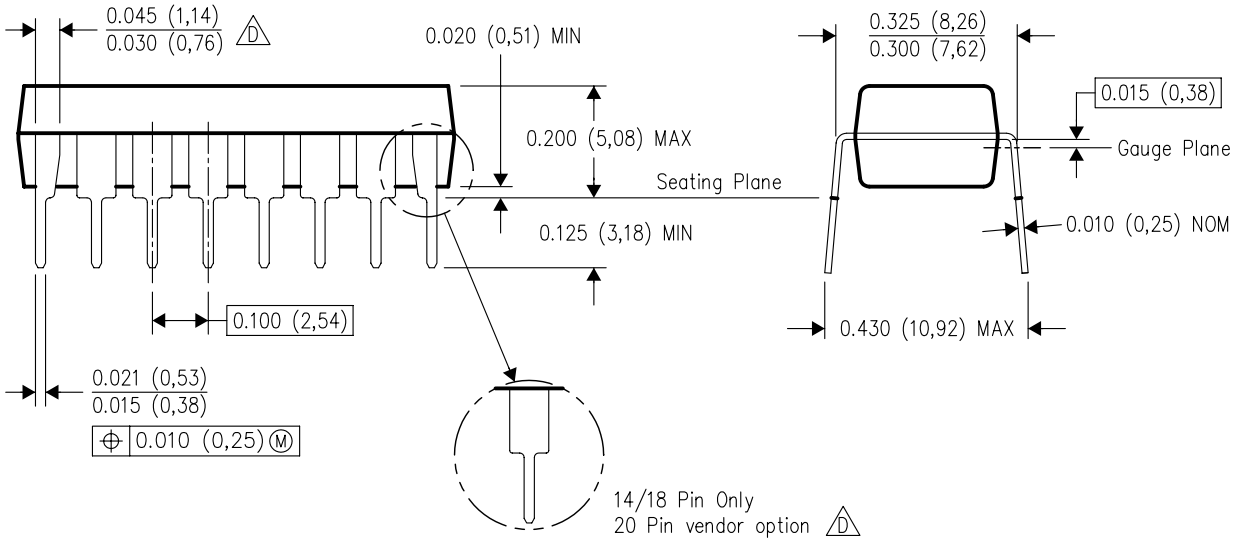
N (R–PDIP–T**)

PLASTIC DUAL–IN–LINE PACKAGE

16 PINS SHOWN



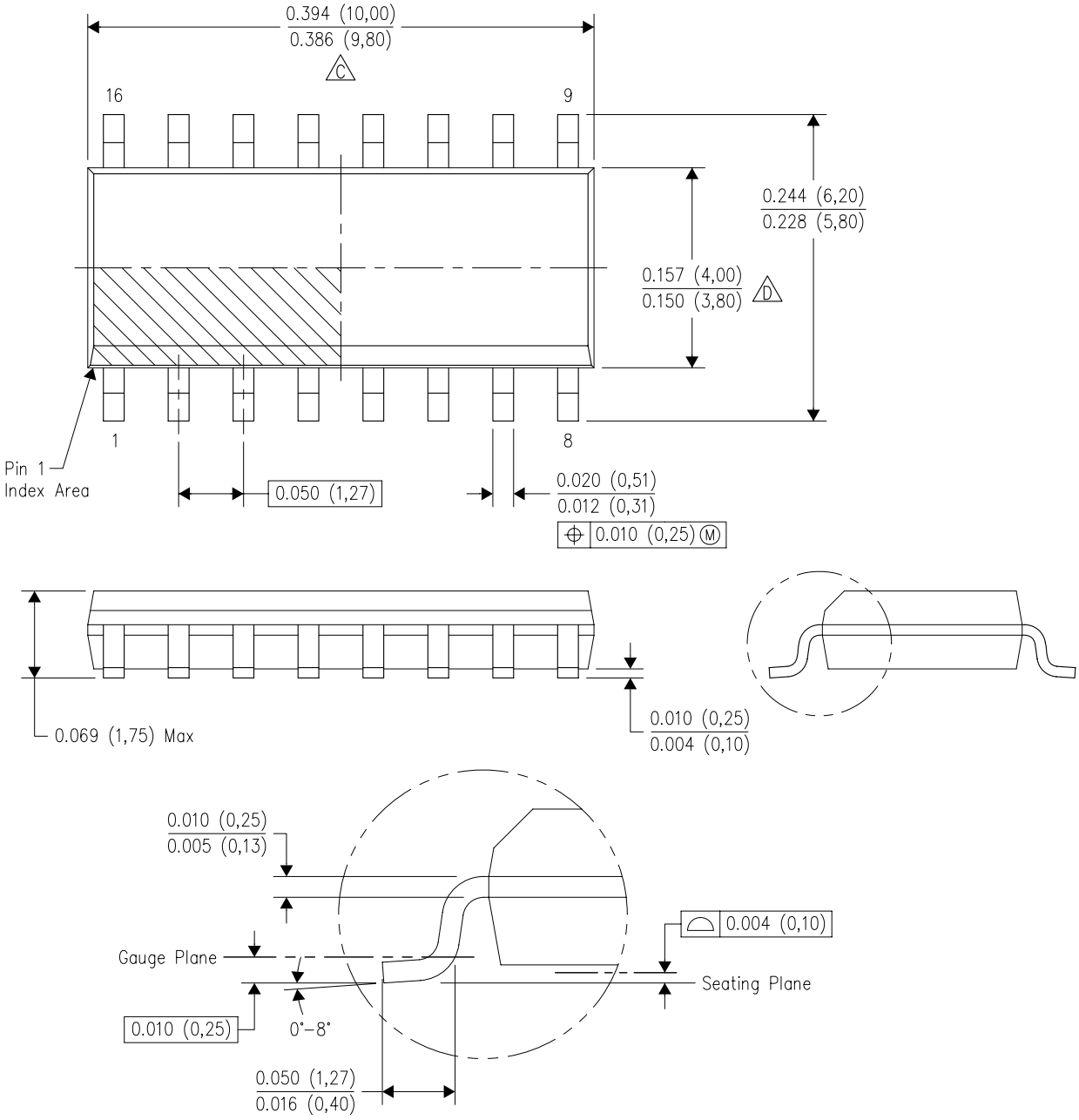
DIM \ PINS **	14	16	18	20
A MAX	0.775 (19,69)	0.775 (19,69)	0.920 (23,37)	1.060 (26,92)
A MIN	0.745 (18,92)	0.745 (18,92)	0.850 (21,59)	0.940 (23,88)
MS–001 VARIATION (C)	AA	BB	AC	AD



4040049/E 12/2002

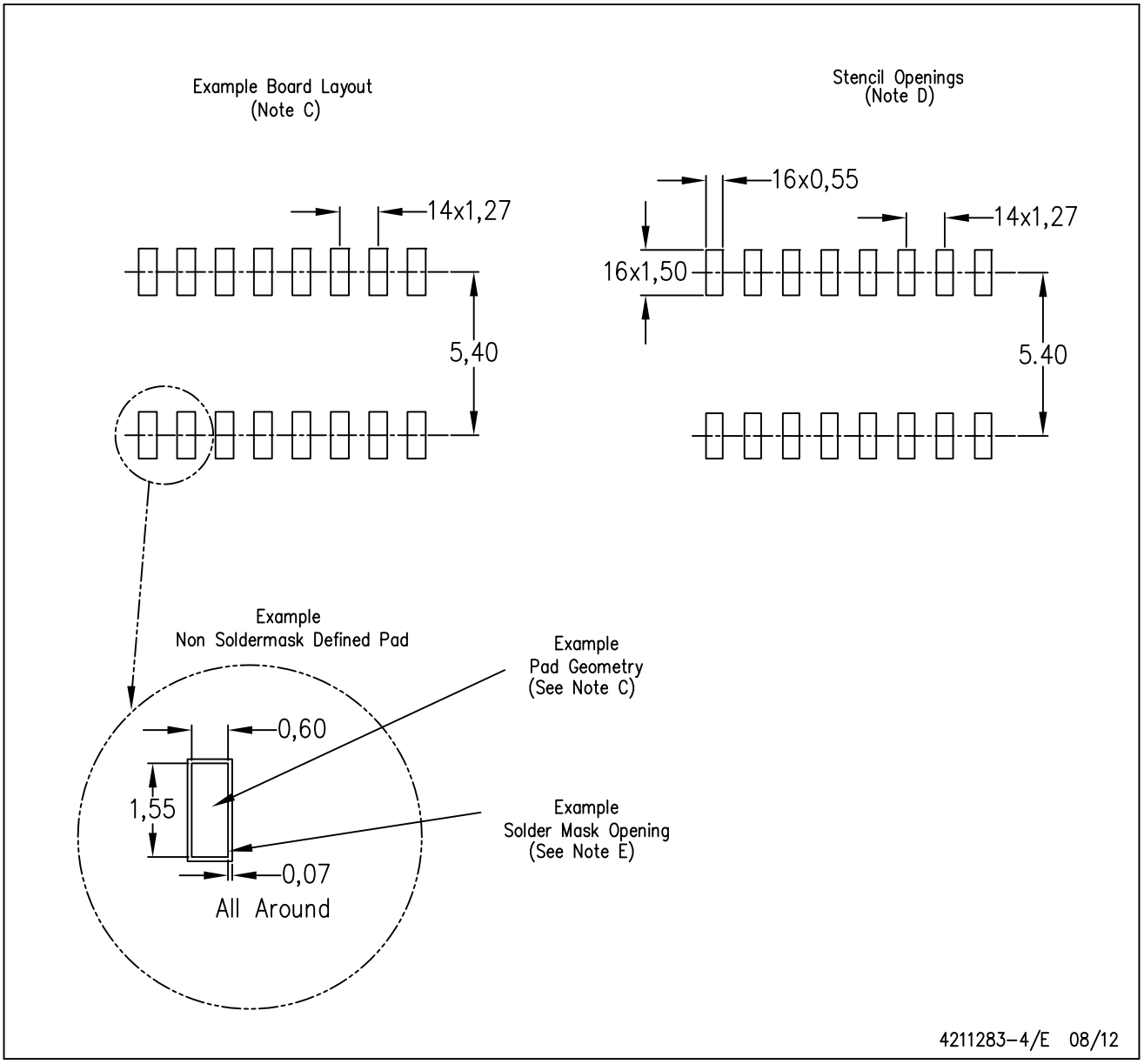
NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Falls within JEDEC MS–001, except 18 and 20 pin minimum body length (Dim A).
D. The 20 pin end lead shoulder width is a vendor option, either half or full width.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE



NOTES:
A. All linear dimensions are in inches (millimeters).
B. This drawing is subject to change without notice.
C. Body length does not include mold flash, protrusions, or gate burrs. Mold flash, protrusions, or gate burrs shall not exceed 0.006 (0,15) each side.
D. Body width does not include interlead flash. Interlead flash shall not exceed 0.017 (0,43) each side.
E. Reference JEDEC MS–012 variation AC.

D (R–PDSO–G16) PLASTIC SMALL OUTLINE

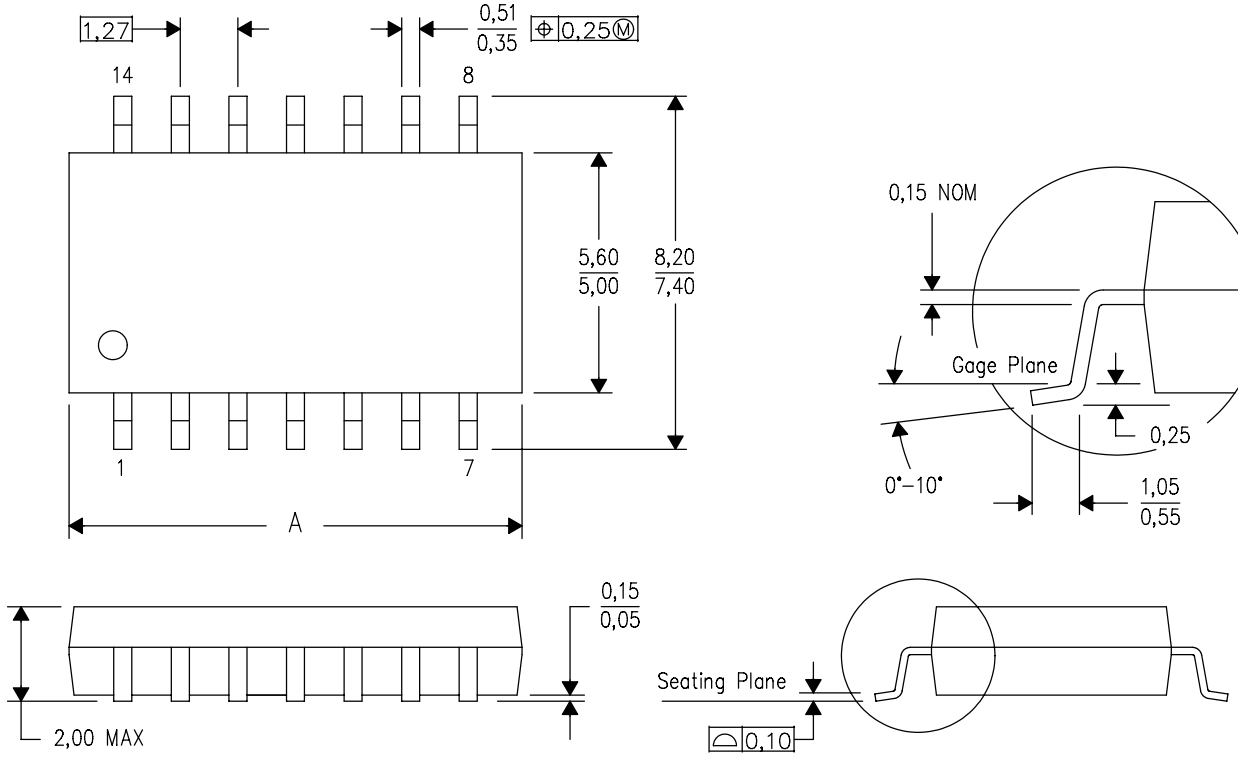


NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Publication IPC–7351 is recommended for alternate designs.
D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC–7525 for other stencil recommendations.
E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

MECHANICAL DATA

NS (R-PDSO-G)** **PLASTIC SMALL-OUTLINE PACKAGE**

14-PINS SHOWN



DIM \ PINS **	14	16	20	24
A MAX	10,50	10,50	12,90	15,30
A MIN	9,90	9,90	12,30	14,70

4040062/C 03/03

NOTES:
A. All linear dimensions are in millimeters.
B. This drawing is subject to change without notice.
C. Body dimensions do not include mold flash or protrusion, not to exceed 0,15.

IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, enhancements, improvements and other changes to its semiconductor products and services per JESD46, latest issue, and to discontinue any product or service per JESD48, latest issue. Buyers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All semiconductor products (also referred to herein as “components”) are sold subject to TI’s terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its components to the specifications applicable at the time of sale, in accordance with the warranty in TI’s terms and conditions of sale of semiconductor products. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by applicable law, testing of all parameters of each component is not necessarily performed.

TI assumes no liability for applications assistance or the design of Buyers’ products. Buyers are responsible for their products and applications using TI components. To minimize the risks associated with Buyers’ products and applications, Buyers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any patent right, copyright, mask work right, or other intellectual property right relating to any combination, machine, or process in which TI components or services are used. Information published by TI regarding third-party products or services does not constitute a license to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of significant portions of TI information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. TI is not responsible or liable for such altered documentation. Information of third parties may be subject to additional restrictions.

Resale of TI components or services with statements different from or beyond the parameters stated by TI for that component or service voids all express and any implied warranties for the associated TI component or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Buyer acknowledges and agrees that it is solely responsible for compliance with all legal, regulatory and safety-related requirements concerning its products, and any use of TI components in its applications, notwithstanding any applications-related information or support that may be provided by TI. Buyer represents and agrees that it has all the necessary expertise to create and implement safeguards which anticipate dangerous consequences of failures, monitor failures and their consequences, lessen the likelihood of failures that might cause harm and take appropriate remedial actions. Buyer will fully indemnify TI and its representatives against any damages arising out of the use of any TI components in safety-critical applications.

In some cases, TI components may be promoted specifically to facilitate safety-related applications. With such components, TI’s goal is to help enable customers to design and create their own end-product solutions that meet applicable functional safety standards and requirements. Nonetheless, such components are subject to these terms.

No TI components are authorized for use in FDA Class III (or similar life-critical medical equipment) unless authorized officers of the parties have executed a special agreement specifically governing such use.

Only those TI components which TI has specifically designated as military grade or “enhanced plastic” are designed and intended for use in military/aerospace applications or environments. Buyer acknowledges and agrees that any military or aerospace use of TI components which have ***not*** been so designated is solely at the Buyer's risk, and that Buyer is solely responsible for compliance with all legal and regulatory requirements in connection with such use.

TI has specifically designated certain components which meet ISO/TS16949 requirements, mainly for automotive use. Components which have not been so designated are neither designed nor intended for automotive use; and TI will not be responsible for any failure of such components to meet such requirements.

Products		**Applications**	
Audio	www.ti.com/audio	Automotive and Transportation	www.ti.com/automotive
Amplifiers	amplifier.ti.com	Communications and Telecom	www.ti.com/communications
Data Converters	dataconverter.ti.com	Computers and Peripherals	www.ti.com/computers
DLP® Products	www.dlp.com	Consumer Electronics	www.ti.com/consumer-apps
DSP	dsp.ti.com	Energy and Lighting	www.ti.com/energy
Clocks and Timers	www.ti.com/clocks	Industrial	www.ti.com/industrial
Interface	interface.ti.com	Medical	www.ti.com/medical
Logic	logic.ti.com	Security	www.ti.com/security
Power Mgmt	power.ti.com	Space, Avionics and Defense	www.ti.com/space-avionics-defense
Microcontrollers	microcontroller.ti.com	Video and Imaging	www.ti.com/video
RFID	www.ti-rfid.com		
OMAP Applications Processors	www.ti.com/omap	**TI E2E Community**	e2e.ti.com
Wireless Connectivity	www.ti.com/wirelessconnectivity		

Mailing Address: Texas Instruments, Post Office Box 655303, Dallas, Texas 75265